

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M7
Core Size	32-Bit Single-Core
Speed	528MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SAI, SPDIF, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	127
Program Memory Size	-
Program Memory Type	External Program Memory
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 20x12b
Oscillator Type	External, Internal
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	196-LFBGA
Supplier Device Package	196-LFBGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mimxrt1051cvl5a

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

FlexIO1 FlexIO2	Flexible Input/output	Connectivity and Communications	The FlexIO is capable of supporting a wide range of protocols including, but not limited to: UART, I2C, SPI, I2S, camera interface, display interface, PWM waveform generation, etc. The module can remain functional when the chip is in a low power mode provided the clock it is using remain active.
FlexPWM1 FlexPWM2 FlexPWM3 FlexPWM4	Pulse Width Modulation	Timer Peripherals	The pulse-width modulator (PWM) contains four PWM sub-modules, each of which is set up to control a single half-bridge power stage. Fault channel support is provided. The PWM module can generate various switching patterns, including highly sophisticated waveforms.
FlexRAM	RAM	Memories	The i.MX RT1050 has 512 KB of on-chip RAM which could be flexible allocated to I-TCM, D-TCM, and on-chip RAM (OCRAM) in a 32 KB granularity. The FlexRAM is the manager of the 512 KB on-chip RAM array. Major functions of this blocks are: interfacing to I-TCM and D-TCM of Arm core and OCRAM controller; dynamic RAM arrays allocation for I-TCM, D-TCM, and OCRAM.
FlexSPI	Quad Serial Peripheral Interface	Connectivity and Communications	FlexSPI acts as an interface to one or two external serial flash devices, each with up to four bidirectional data lines.

- No external component required
- Starts up quicker than 32 kHz crystal oscillator
- External crystal oscillator with on-chip support circuit:
 - At power up, ring oscillator is utilized. After crystal oscillator is stable, the clock circuit switches over to the crystal oscillator automatically.
 - Higher accuracy than ring oscillator
 - If no external crystal is present, then the ring oscillator is utilized

The decision of choosing a clock source should be taken based on real-time clock use and precision time-out.

4.1.5 Maximum supply currents

The data shown in Table 11 represent a use case designed specifically to show the maximum current consumption possible. All cores are running at the defined maximum frequency and are limited to L1 cache accesses only to ensure no pipeline stalls. Although a valid condition, it would have a very limited practical use case, if at all, and be limited to an extremely low duty cycle unless the intention were to specifically show the worst case power consumption.

See the i.MX RT1050 Power Consumption Measurement Application Note for more details on typical power consumption under various use case definitions.

Power Rail	Conditions	Max Current	Unit	
DCDC_IN	Max power for FF chip at 105 °C	100	mA	
VDD_HIGH_IN	Include internal loading in analog	50	mA	
VDD_SNVS_IN	—	250	А	
USB_OTG1_VBUS USB_OTG2_VBUS	25 mA for each active USB interface	50	mA	
VDDA_ADC_3P3	 3.3 V power supply for 12-bit ADC, 600 A typical, 750 A max, for each ADC. 100 Ohm max loading for touch panel, cause 33 mA current. 	40	mA	
NVCC_GPIO NVCC_SD0 NVCC_SD1 NVCC_EMC	C—Equivalent external capacitive load V—IO voltage (0.5 x F)—Data change rate. Up to 0.5 of	Where: N—Number of IO pins supplied by the power line C—Equivalent external capacitive load		

Table 11. Maximum supply currents

NOTE

The currents on the VDD_HIGH_CAP and VDD_USB_CAP were identified to be the voltage divider circuits in the USB-specific level shifters.

4.2 System power and clocks

This section provide the information about the system power and clocks.

4.2.1 Power supplies requirements and restrictions

The system design must comply with power-up sequence, power-down sequence, and steady state guidelines as described in this section to guarantee the reliable operation of the device. Any deviation from these sequences may result in the following situations:

- Excessive current during power-up phase
- Prevention of the device from booting
- Irreversible damage to the processor (worst-case scenario)

4.2.1.1 **Power-up sequence**

The below restrictions must be followed:

- VDD_SNVS_IN supply must be turned on before any other power supply or be connected (shorted) with VDD_HIGH_IN supply.
- If a coin cell is used to power VDD_SNVS_IN, then ensure that it is connected before any other supply is switched on.
- When internal DCDC is enabled, external delay circuit is required to delay the "DCDC_PSWITCH" signal 1 ms after DCDC_IN is stable.
- POR_B should be held low during the entire power up sequence.

NOTE

The POR_B input (if used) must be immediately asserted at power-up and remain asserted until after the last power rail reaches its working voltage. In the absence of an external reset feeding the POR_B input, the internal POR module takes control. See the i.MX RT1050 Reference Manual (IMXRT1050_RM) for further details and to ensure that all necessary requirements are being met.

NOTE

Need to ensure that there is no back voltage (leakage) from any supply on the board towards the 3.3 V supply (for example, from the external components that use both the 1.8 V and 3.3 V supplies).

NOTE

USB_OTG1_VBUS, USB_OTG2_VBUS, and VDDA_ADC_3P3 are not part of the power supply sequence and may be powered at any time.

i.MX RT1050 Crossover Processors for Industrial Products, Rev. 1, 03/2018

Electrical characteristics

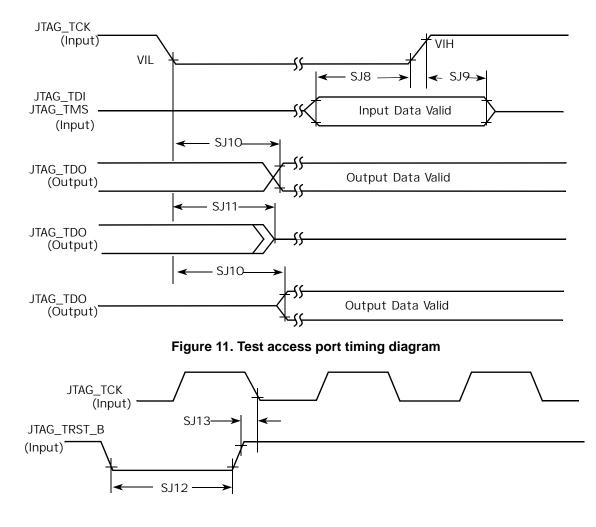


Table 29	JTAG	timing
----------	------	--------

ID	Parameter ^{1,2}	All Freq	Unit	
		Min	Мах	onit
SJ0	JTAG_TCK frequency of operation 1/(3•T _{DC}) ¹	0.001	22	MHz
SJ1	JTAG_TCK cycle time in crystal mode	45	—	ns
SJ2	JTAG_TCK clock pulse width measured at V_M^2	22.5	—	ns
SJ3	JTAG_TCK rise and fall times	—	3	ns
SJ4	Boundary scan input data set-up time	5	—	ns
SJ5	Boundary scan input data hold time	24	—	ns
SJ6	JTAG_TCK low to output data valid	—	40	ns
SJ7	JTAG_TCK low to output high impedance	—	40	ns
SJ8	JTAG_TMS, JTAG_TDI data set-up time	5	—	ns

i.MX RT1050 Crossover Processors for Industrial Products, Rev. 1, 03/2018

Electrical characteristics

Figure 43 shows MII traints signal timing suble 63 describes the timing openators (M5 M8) shown in the figure.

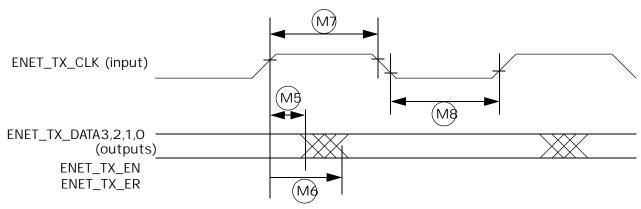


Figure 43. MII transmit signal timing diagram

Table 63. MII transmit signal timing

ID	Characteristic ¹	Min.	Max.	Unit
M5	ENET_TX_CLK to ENET_TX_DATA3,2,1,0, ENET_TX_EN, ENET_TX_ER invalid	5	—	ns
M6	ENET_TX_CLK to ENET_TX_DATA3,2,1,0, ENET_TX_EN, ENET_TX_ER valid	—	20	ns
M7	ENET_TX_CLK pulse width high	35%	65%	ENET_TX_CLK period
M8	ENET_TX_CLK pulse width low	35%	65%	ENET_TX_CLK period

¹ ENET_TX_EN, ENET_TX_CLK, and ENET0_TXD0 have the same timing in 10-Mbps 7-wire interface mode.

4.9.4.1.3 MII asynchronous inputs signal timing (ENET_CRS and ENET_COL)

Figure 44 shows MII asynchronous input til and the scribes the timing operator (M9) shown in the figure.

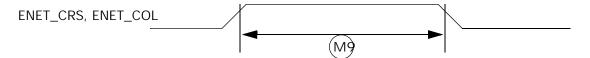


Figure 44. MII asynchronous inputs timing diagram

ID	Characteristic	Min.	Max.	Unit
M9 ¹	ENET_CRS to ENET_COL minimum pulse width	1.5	_	ENET_TX_CLK period

¹ ENET_COL has the same timing in 10-Mbit 7-wire interface mode.